

## DS1259

Battery Manager Chip

Not Recommended for New Designs		
Part Number	Replacement	Explanation
DS1259	n/a	This product is being discontinued and is subject to Last Time Buy, after which new orders can not be placed.
DS1259+	n/a	
DS1259N	n/a	
DS1259S	n/a	
DS1259S+	n/a	
DS1259SN	n/a	
DS1259SN+	n/a	

### Description

The DS1259 Battery Manager Chip is a low-cost battery management system for portable and nonvolatile electronic equipment. A battery connected to the battery input pin supplies power to CMOS electronic circuits when primary power is lost through an efficient switch via the  $V_{CC0}$  pins. When power is supplied from the battery, the power-fail signal is active to warn electronic reset circuits of the power status. Energy loss during shipping and handling is avoided by pulsing reset, thereby causing the battery to be isolated from other elements in the circuits.

### Key Features

- Facilitates uninterruptible power
- Uses battery only when primary  $V_{CC}$  is not available
- Low forward voltage drop
- Power fail signal interrupts processor or write protects memory
- Consumes less than 100nA of battery current
- Low battery warning signal
- Battery can be electrically disconnected upon command
- Battery will automatically reconnect when  $V_{CC}$  is applied
- Mates directly with DS1212 Nonvolatile Controller x 16 Chip to back up 16 RAMs
- Optional 16-pin SOIC surface-mount package
- Underwriters Laboratories (UL®) Recognized

### Evaluation Kits

none

### Reliability Reports

Reliability Report: [DS1259.pdf](#)  
Underwriters Laboratories (UL®) Recognized

### Software/Models

none

### Ordering Information

## Notes:

1. Other options and links for purchasing parts are listed at:
2. [Didn't Find What You Need?](#) Ask our applications engineers. Expert assistance in finding parts, usually within one business day.
3. Part number suffixes: T or T&R = tape and reel; + = RoHS/lead-free; # = RoHS/lead-exempt. More: See [Full Data Sheet](#) or [Part Naming Conventions](#).
4. \* Some packages have variations, listed on the drawing. "PkgCode/Variation" tells which variation the product uses. Note that "+", "#", "-" in the part number suffix describes RoHS status. Package drawings may show a different suffix character.

## Devices: 1-11 of 11

DS1259	Free Sample	Buy	Package: TYPE PINS FOOTPRINT DRAWING CODE/VAR *	Temp	RoHS/Lead-Free? Materials Analysis
DS1259+			PDIP; 16 pin; Dwg: <a href="#">21-0043</a> (PDF) Use pkgcode/variation: P16+2*	0°C to +70°C	RoHS/Lead-Free: <a href="#">Lead Free Materials Analysis</a>
DS1259			PDIP; 16 pin; Dwg: <a href="#">21-0043</a> (PDF) Use pkgcode/variation: P16-2*	0°C to +70°C	RoHS/Lead-Free: <a href="#">No Materials Analysis</a>
DS1259N			PDIP; 16 pin; Dwg: <a href="#">21-0043</a> (PDF) Use pkgcode/variation: P16-2*	-40°C to +85°C	RoHS/Lead-Free: <a href="#">No Materials Analysis</a>
DS1259S+T&R			SOIC; 16 pin; Dwg: <a href="#">21-0042</a> (PDF) Use pkgcode/variation: W16+3*	0°C to +70°C	RoHS/Lead-Free: <a href="#">Lead Free Materials Analysis</a>
DS1259SN+			SOIC; 16 pin; Dwg: <a href="#">21-0042</a> (PDF) Use pkgcode/variation: W16+11*	-40°C to +85°C	RoHS/Lead-Free: <a href="#">Lead Free Materials Analysis</a>
DS1259SN+T&R			SOIC; 16 pin; Dwg: <a href="#">21-0042</a> (PDF) Use pkgcode/variation: W16+11*	-40°C to +85°C	RoHS/Lead-Free: <a href="#">Lead Free Materials Analysis</a>
DS1259S			SOIC; 16 pin; Dwg: <a href="#">21-0042</a> (PDF) Use pkgcode/variation: W16-11*	0°C to +70°C	RoHS/Lead-Free: <a href="#">No Materials Analysis</a>
DS1259S+			SOIC; 16 pin; Dwg: <a href="#">21-0042</a> (PDF) Use pkgcode/variation: W16+11*	0°C to +70°C	RoHS/Lead-Free: <a href="#">Lead Free Materials Analysis</a>
DS1259S/T&R			SOIC; 16 pin; Dwg: <a href="#">21-0042</a> (PDF) Use pkgcode/variation: W16-11*	0°C to +70°C	RoHS/Lead-Free: <a href="#">No Materials Analysis</a>
DS1259SN			SOIC; 16 pin; Dwg: <a href="#">21-0042</a> (PDF) Use pkgcode/variation: W16-11*	-40°C to +85°C	RoHS/Lead-Free: <a href="#">No Materials Analysis</a>
DS1259SN/T&R			SOIC; 16 pin; Dwg: <a href="#">21-0042</a> (PDF) Use pkgcode/variation: W16-11*	-40°C to +85°C	RoHS/Lead-Free: <a href="#">No Materials Analysis</a>

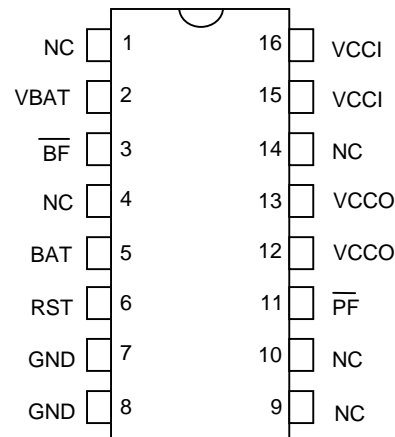
### FEATURES

- Facilitates uninterruptible power
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- Optional 16-pin SOIC surface-mount package

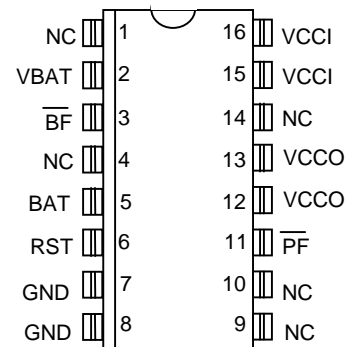
### PIN DESCRIPTION

NC	- No Connect
$V_{BAT}$	- Battery Input Connection
$\overline{BF}$	- Battery Fail Output Signal
BAT	- Battery Output
RST	- Reset Input
GND	- Ground
$\overline{PF}$	- Power Fail Output Signal
$V_{CCO}$	- RAM Supply
$V_{CCI}$	- +5V Supply

### PIN ASSIGNMENT



16-Pin DIP Package (300-mil)  
See Mech. Drawings Section



16-Pin SOIC Package (300-mil)  
See Mech. Drawings Section

### DESCRIPTION

The DS1259 Battery Manager Chip is a low-cost battery management system for portable and nonvolatile electronic equipment. A battery connected to the battery input pin supplies power to CMOS electronic circuits when primary power is lost through an efficient switch via the  $V_{CCO}$  pins. When power is supplied from the battery, the power-fail signal is active to warn electronic reset circuits of the power status. Energy loss during shipping and handling is avoided by pulsing reset, thereby causing the battery to be isolated from other elements in the circuits.

**ABSOLUTE MAXIMUM RATINGS\***

Voltage on Any Pin Relative to Ground	-0.3V to +7.0V
Operating Temperature	0°C to 70°C
Storage Temperature	-55°C to +125°C
Soldering Temperature	260°C for 10 seconds

\* This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operation sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect reliability.

**RECOMMENDED DC OPERATING CONDITIONS** (0°C to 70°C)

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Primary Power Supply	V <sub>CCI</sub>		5	5.5	V	1
Input High Voltage	V <sub>IH</sub>	2.0		V <sub>CC</sub> +0.3	V	1
Input Low Voltage	V <sub>IL</sub>	-0.3		+0.8	V	1
Battery Voltage Pin 2	V <sub>BAT</sub>	2.5	3	3.7	V	6
Battery Output Pin 5	BAT	V <sub>BAT</sub> -0.1			V	1

**DC ELECTRICAL CHARACTERISTICS** (0°C to 70°C; V<sub>CC</sub> = 4.5 to 5.5V)

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Leakage Current	I <sub>LO</sub>	-1.0		+250	μA	
Output Current @ 2.4V	I <sub>OH</sub>	-1.0			mA	1, 2
Output Current @ 0.4V	I <sub>OL</sub>			+4.0	mA	1, 2
Input Supply Current	I <sub>CCI</sub>			10	mA	3
Pins 12, 13 V <sub>CCO</sub> =V <sub>CCI</sub> -0.2	I <sub>CCO</sub>			250	mA	
Pin 11 $\overline{\text{PF}}$ Detect	V <sub>TP</sub>	(1.26xV <sub>BAT</sub> ) -250mV	(1.26xV <sub>BAT</sub> ) +250mV		V	4, 6
Pin 3 $\overline{\text{BF}}$ Detect	V <sub>BATF</sub>	1.5	2.0	2.6	V	7

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Pins 12, 13 V <sub>CCO</sub> =V <sub>BAT</sub> -0.2V	I <sub>CCO2</sub>			15	mA	5
Battery Leakage	I <sub>BAT</sub>			100	nA	8
Pin 5 Battery Output Current	I <sub>BATOUT</sub>			100	μA	

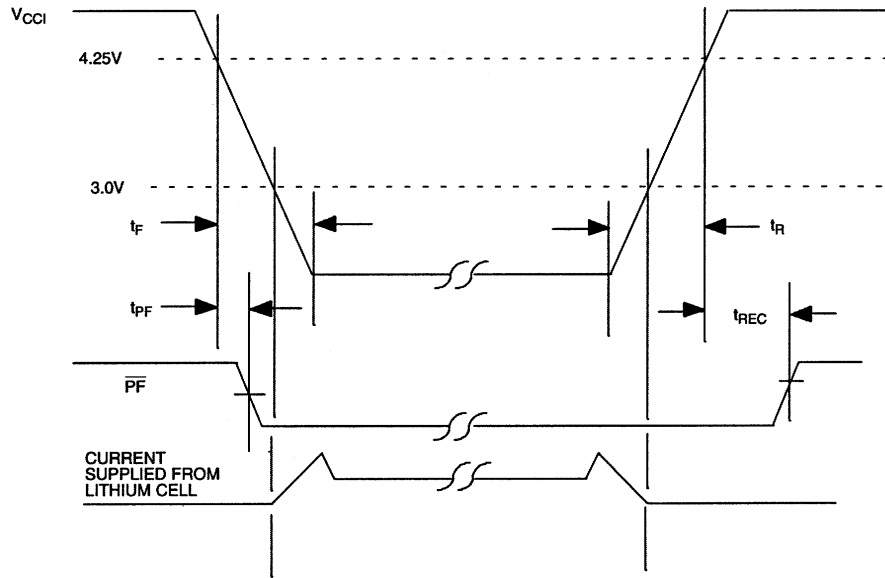
**CAPACITANCE** (T<sub>A</sub> = 25°C)

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Input Capacitance	C <sub>IN</sub>		5	10	pF	
Output Capacitance	C <sub>OUT</sub>		5	10	pF	

**AC ELECTRICAL CHARACTERISTICS** (0°C to 70°C; V<sub>CC</sub> = 4.0 to 5.5V)

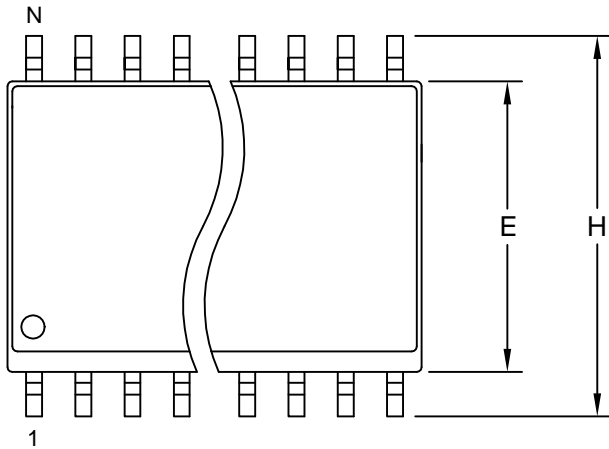
PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
V <sub>CCI</sub> Slew Rate	t <sub>F</sub>	300			μs	
V <sub>CCI</sub> Slew Rate	t <sub>R</sub>	1			μs	
Power-Down to $\overline{\text{PF}}$ Low	t <sub>PF</sub>	0			μs	
$\overline{\text{PF}}$ High after Power-Up	t <sub>REC</sub>			100	μs	9

## POWER-DOWN/POWER-UP CONDITION

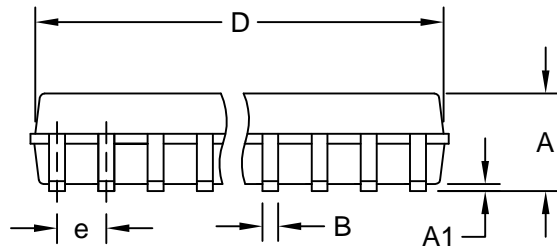


### NOTES:

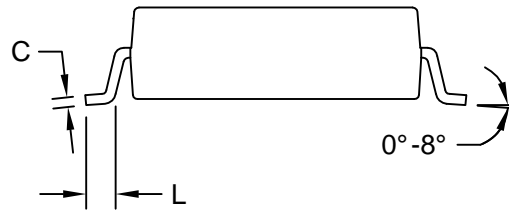
1. All voltages are referenced to ground.
2. Load capacity is 50 pF.
3. Measured with Pins 11, 12, 13, and 3 open.
4.  $V_{TP}$  is the point that  $\overline{PF}$  is driven low.
5.  $I_{CCO2}$  may be limited by the capability of the battery.
6. Trip point voltage for power-fail detect:  
 $V_{TP} = 1.26 \times V_{BAT} \pm 250 \text{ mV}$   
 For 5% operation:  $V_{BAT} = 3.7\text{V max.}$   
 For 10% operation:  $V_{BAT} = 3.5\text{V max.}$
7.  $V_{BATF}$  is the point that  $\overline{BF}$  is driven low. These limits are for  $0^\circ\text{C}$  to  $70^\circ\text{C}$  operation.
8. Battery leakage is the internal energy consumed by the DS1259.
9.  $V_{CC} = +5 \text{ volts}$ ,  $t_A = 25^\circ\text{C}$ .



TOP VIEW



FRONT VIEW



SIDE VIEW



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.093	0.104	2.35	2.65
A1	0.004	0.012	0.10	0.30
B	0.014	0.019	0.35	0.49
C	0.009	0.013	0.23	0.32
e	0.050		1.27	
E	0.291	0.299	7.40	7.60
H	0.394	0.419	10.00	10.65
L	0.016	0.050	0.40	1.27

VARIATIONS:

DIM	INCHES		MILLIMETERS		N	MS013
	MIN	MAX	MIN	MAX		
D	0.398	0.413	10.10	10.50	16	AA
D	0.447	0.463	11.35	11.75	18	AB
D	0.496	0.512	12.60	13.00	20	AC
D	0.598	0.614	15.20	15.60	24	AD
D	0.697	0.713	17.70	18.10	28	AE

NOTES:

1. D&E DO NOT INCLUDE MOLD FLASH.
2. MOLD FLASH OR PROTRUSIONS NOT TO EXCEED 0.15mm (.006").
3. LEADS TO BE COPLANAR WITHIN 0.10mm (.004").
4. CONTROLLING DIMENSION: MILLIMETERS.
5. MEETS JEDEC MS013.
6. N = NUMBER OF PINS.

 			
<small>PROPRIETARY INFORMATION</small>			
<small>TITLE:</small> <b>PACKAGE OUTLINE, .300" SOIC</b>			
<small>APPROVAL</small>	<small>DOCUMENT CONTROL NO.</small> <b>21-0042</b>	<small>REV.</small> <b>B</b>	<b>1/1</b>